

## **OPTICAL RECEIVER AND TRANSCEIVER USING THE SAME**

The present invention relates to an optical receiver for receiving an optical signal, for converting the optical signal into an electric signal and for outputting the electrical signal.

5 Particularly, the optical receiver is an optical data receiver for receiving data at a predetermined data rate. The present invention also relates to a transceiver including the optical receiver/optical data receiver of the present invention and a transmitter for receiving an electric signal, converting the electric signal into an optical signal and outputting the optical signal.

10 In order to support the communication requirements of high-speed data transmission applications (for instance, at a bit rate of 25 Gpbs) optical links are used when links via an electrical wire have a too low bandwidth. When using an optical link for transmitting a signal from a first electronic component to a second electronic component, the electric signal to be transmitted is first converted into an optical signal, then the optical signal is  
15 coupled into an optical fiber via an optical transmitter and transmitted to the second electronic component via the optical fiber. At the second electronic component the optical signal is received via an optical receiver and converted into an electrical signal. Then the converted electrical signal is further processed in the second electronic component.

Fig. 1 shows a transceiver 100 of the state-of-the-art that is used for converting an electric  
20 signal into an optical signal and vice-versa. The transceiver 100 includes a dielectric non-conductive substrate (not shown in Fig. 1), a ground plane 101 placed on the dielectric non-conductive substrate, an array of four drivers 102, an array of four laser diodes 103 (for instance, vertical cavity surface emitting lasers, abbreviated VCSEL) that are connected to respective outputs of the drivers 102, an array of four photodiodes 104 (for  
25 instance, positive intrinsic negative diodes, abbreviated PINs), and an array of four transimpedance amplifiers 105 (abbreviated TIAs) connected to respective outputs of the photodiodes of the array of photodiodes 104. The array of drivers 102, the array of laser diodes 103, the array of photodiodes 104 and the array of TIAs 105 are all placed on the same dielectric non-conductive substrate and surrounded by the ground plane 101.

Additionally, the array of photodiodes 104 is placed in the interior of an opening provided in the ground plane 101, so as to isolate the array of photodiodes 104 from the ground plane 101.

Each driver of the driver array 102 receives at its input (not shown in Fig. 1) an electric signal from, for instance, a motherboard of a computer (not shown in Fig. 1), converts the received electrical signal into a single ended electrical signal, and outputs this via output terminals 110 and 111 to inputs of a VCSEL of the VCSEL array 103. The output terminal 111 of a driver of the driver array 102 is connected via a ground line 113 to an input of a respective VCSEL of the VCSEL array 103. The output terminal 110 of a driver of the driver array 102 is connected via a signal line 112 to another input of the respective VCSEL. Each VCSEL of the VCSEL array 103 converts the single ended electrical signal received at its inputs to an optical signal, and outputs this to an optical fiber.

Each photodiode 114 of the array of photodiodes 104 receives an optical signal from, for instance an optical fiber (not shown in Fig. 1), converts the received optical signal into a single ended electrical signal, and outputs this via its anode 117 and its cathode 116 to the inputs of a respective TIA. The anode 117 of a photodiode of the array of photodiodes 104 is connected via a signal line 118 to an input of the respective TIA, and the cathode 116 of a photodiode of the array of photodiodes 104 is connected via a ground line 119 to another input of the respective TIA.

As the signal lines connecting outputs of the driver array 102 with respective inputs of the VCSEL array 103 (in the following denoted as Driver-VCSEL channels) and the signal lines connecting anodes 114 of the photodiode array 104 with respective inputs of the TIA array 105 (in the following denoted as PIN-TIA channels) are of single end type, single-end-type crosstalk occurs among these lines, i.e. a transfer of signal power from one or a plurality of signal lines (aggressor lines) to another signal line (victim line) via the common ground plane 101. At the victim line crosstalk overlays with the signal carried by the victim line, thereby degrading its signal quality. Crosstalk can occur among Driver-VCSEL channels, among PIN-TIA channels, but also among Driver-VCSEL channels and PIN-TIA channels, if the array of photodiodes 104 is isolated from ground by the opening 115 provided in the ground plane 101.

The opening 115 formed in the ground plane 101 and surrounding the photodiode array 104 has a rectangular shape and a size of approximately 1 mm x 0.4 mm. The size of the opening is mainly determined by the dimensions of the photodiode array 104 and cannot be reduced arbitrarily. At high frequencies opening 105 acts as a slot resonator whose  
 5 fundamental frequency is mainly determined by the geometric dimension of the opening 105. A rectangular opening having a size of 1 mm x 0.4 mm has a resonant frequency of about 38 GHz. This is about 3 x 12.5 GHz, wherein 12.5 GHz is the fundamental frequency of the 25 Gbps data transmission. As the opening 115 acts as a slot resonator whose fundamental frequency is almost a multiple of the fundamental frequency of the 25  
 10 Gbps data transmission, the opening 115 attracts signal current output by drivers of the driver array 102. This resonant effect, which occurs at approximately 38 GHz, promotes crosstalk from Driver-VCSEL channels to PIN-TIA channels. Particularly, PIN-TIA channels that are placed near to the driver array 102 are affected by crosstalk coming from Driver-VCSEL channels.

Fig. 2 shows the principle s-parameter coupling coefficient corresponding to the single end type crosstalk from the driver outputs of the driver array 102 to the input of the TIA that is closest to the driver array 102. This is obtained by simulation for the transceiver 100 having all Driver-VCSEL channels (aggressors) activated. The principle s-parameter coupling coefficient 201 exhibits a broad resonance 202 at 38 GHz due to the resonance  
 20 effect of the opening 115. This resonance 202 induces crosstalk in the TIA input closest to the driver array 102. This crosstalk generates more than 6 ps or 0.15 UI Jitter in the EYE diagram for 25 Gbps, assuming a bit error rate (BER) of  $10^{-12}$ . This becomes evident from Fig. 3, which shows the EYE diagram corresponding to 25 Gbps, for the PIN-TIA channel closest to the driver array 102. The EYE diagram in Fig. 3 has been obtained by simulation  
 25 under the conditions that the transceiver 100 has all four aggressor channels activated and the ratio between driver output and TIA input current is equal to 100, which corresponds to about -8 dBm optical receiver sensitivity. The outline 301 corresponds to a bit error rate of  $10^{-12}$ .

The resonant behavior of the opening 115 also promotes crosstalk among PIN-TIA  
 30 channels. This increases with increasing number of photodiodes included in the array of

photodiodes 104. When the photodiode array 104 includes 8 or 12 channels, the crosstalk level among PIN-TIA channels can reach an intolerable value.

For a photodiode array including twelve channels, the opening provided in the ground plane and surrounding the photodiode array exhibits a resonance at about 15 GHz. This resonance is close to the fundamental frequency of the 25 Gbps data transmission (which is 12.5 GHz) and thus also promotes crosstalk, thereby degrading signal quality of the PIN-TIA channels.

Crosstalk in the PIN-TIA channels severely degrade the signal quality of the signals input to the TIA array 105, especially of those input to TIAs that are close to the driver array 102.

It is therefore an object of the present invention to reduce crosstalk in the PIN-TIA channels of an optical receiver.

This object is achieved by the features as set forth in claim 1. Further advantageous embodiments of the present invention are set forth in the dependent claims.

The present invention is based on the idea that crosstalk of an electric signal in a PIN-TIA channel of an optical receiver can be effectively reduced by moving the resonant frequency of the opening that isolates the array of photodiodes from the ground plane to a frequency that is sufficiently higher than three times of the fundamental frequency of the crosstalking electric signal.

**Fig. 1** shows a schematic of a transceiver of the state of the art;

**Fig. 2** shows the principle s-parameter coupling coefficient corresponding to the single end type crosstalk from the driver outputs to the input of the TIA closest to the driver array for the transceiver of the state of the art;

**Fig. 3** shows the EYE diagram corresponding to 25 Gbps for the PIN-TIA channel closest to the driver array in the transceiver of the state of the art;

**Fig. 4** shows a schematic of an optical receiver according to a first embodiment of the present invention;

**Fig. 5** shows a schematic of an optical receiver according to a second embodiment of the present invention;

**Fig. 6** shows a schematic of a transceiver including the optical receiver according to the first embodiment of the present invention;

5 **Fig. 7** shows a schematic of a transceiver including the optical receiver according to the second embodiment of the present invention;

**Fig. 8** shows a layout of a mask of the optical receiver according to the second embodiment of the present invention;

10 **Fig. 9** shows the principle s-parameter coupling coefficient corresponding to the single end type crosstalk from the driver outputs to the input of the TIA closest to the driver array for the transceiver including the optical receiver according to the second embodiment of the present invention;

15 **Fig. 10** shows the EYE diagram corresponding to 25 Gbps for the PIN-TIA channel closest to the driver array in the transceiver including the optical receiver according to the second embodiment of the present invention;

Referring now to Fig. 4, a first advantageous embodiment of an optical receiver according to the present invention, is shown. Fig. 4 shows an optical receiver 400 including a dielectric non-conductive substrate (not shown in Fig. 1), a ground plane 401 placed on the dielectric non-conductive substrate, an array of four photodiodes 404 (e.g. PINs), and an array of four amplifiers 405 (e.g. TIAs) connected to respective outputs of the photodiodes. The array of photodiodes 404 and the array of amplifiers 405 are placed on the dielectric non-conductive substrate and surrounded by the ground plane 401. Four openings 415 are provided in the ground plane 401. Each opening of the four openings 415 surrounds one photodiode 414 so as to isolate the respective photodiode from the ground plane.

25 Each photodiode 414 of the array of photodiodes 404 receives an optical signal from, for instance, an optical fibre (not shown in Fig. 4), converts the received optical signal into a single ended electrical signal, and outputs this via its anode 417 and cathode 416 to the inputs of a respective amplifier. The anode 417 of a photodiode of the array of photodiodes

404 is connected via signal line 418 to an input of the respective amplifier, and the cathode 416 of a photodiode of the array of photodiodes 404 is connected via a ground line 419 to another input of the respective amplifier.

Each opening 415 of the four openings has a rectangular shape and a size of approximately 0.3 mm x 0.25 mm, so that its resonance frequency is sufficiently higher than 37.5 GHz, preferably 50 GHz or higher. Thus, for this embodiment sufficiently higher is achieved by setting the resonance frequency of the slot resonance to 50 GHz or higher. The minimal length of an opening 415 in the length's direction of the array of photodiodes 404 is determined by the dimensions of a photodiode 414, particularly by the distance between anode and cathode along the optical aperture, and cannot be reduced arbitrarily. As the resonant frequency of each opening 415 of the four openings is sufficiently higher than three times 12.5 GHz, which is the fundamental frequency of the 25 Gbps data transmission, the opening does not act as a slot resonator with the fundamental frequency of 37.5 GHz. Consequently, the opening does not attract signal current via the ground plane if the optical receiver 400 and, for instance, an 25 Gbps data transmitter are placed on the same non-conductive substrate.

As the openings 415 provided in the ground plane 401 of the optical receiver according to the first embodiment of the present invention, do not show a resonant effect at 37.5 GHz, crosstalk of an external signal with a fundamental frequency of 12.5 GHz into the signal line connecting the anode of a photodiode 414 and the input of a respective amplifier (in the following denoted as PIN-TIA channels) is significantly reduced compared to the transceiver of the state of the art 100.

The openings 415 provided in the ground plane 401 also reduce crosstalk between individual PIN-TIA channels of the optical receiver 400 if the fundamental frequency of the signals output by the photodiodes of the array of photodiodes 404 is about 12.5 GHz.

Referring now to Fig. 5, a second advantageous embodiment of an optical receiver according to the present invention, is shown. The optical receiver according to the second embodiment 500 differs from the optical receiver according to the first receiver in that each opening 415 of the optical receiver according to the first embodiment is divided into a first opening 515 and a second opening 525. The first opening 515 and the second opening 525

are separated from each other by a strip line 530 that is connected to the ground plane 501 at both ends. A first opening 515 is an opening that surrounds a photodiode 514 of the array of photodiodes 504, whereas a second opening 525 is an opening that does not surround a photodiode 514 of the array of photodiodes 504. A first opening 515 and its  
 5 corresponding second opening 525 are placed next to each other. Preferentially, the area of a second opening 525 is smaller than the area of its corresponding first opening 514.

As an opening 415 of the optical receiver according to the first embodiment has a resonance frequency that is sufficiently higher than three times of a predetermined fundamental frequency, the first opening 515 and the second opening 525 of the optical  
 10 receiver according to the second embodiment have resonant frequencies that are sufficiently higher than three times of the predetermined fundamental frequency. It is essential that each of the first opening 515 and the second opening 525 of the optical receiver according to the second embodiment has a resonant frequency that is sufficiently higher than three times of a predetermined fundamental frequency.

15 Although the ground plane 501 of the optical receiver according to the second embodiment includes a first opening 515 and a second opening 525 for each photodiode 514 of the array of photodiodes 504, it is conceivable for the present invention that the first opening 515 and the second opening 525 is provided in the ground plane 501 only for a part of the photodiodes of the array of photodiodes 504.

20 Placing a second opening 525 next to a first opening 515, which surrounds a photodiode 514 of the array of photodiodes 504, reduces crosstalk in the PIN-TIA channels of the optical receiver according to the second embodiment more effectively.

Referring now to Fig. 6, a third advantageous embodiment according to the present invention is shown. Fig. 6 shows a transceiver including the optical receiver according to  
 25 the first embodiment.

The transceiver 600 includes a dielectric non-conductive substrate (not shown in Fig. 6) a ground plane 601 placed on the dielectric non-conductive substrate, an array of four drivers 602, an array of four laser diodes (VCSEL) 603 that are connected to respective outputs of the drivers of the array of drivers 602, and an optical receiver 650. In Fig. 6, the optical

receiver 650 is encircled with the dotted line 651. As the structure of the optical receiver 650 is identical to the optical receiver according to the first embodiment 400, a detailed description of the optical receiver 650 is omitted herein. The array of drivers 602, the array of laser diodes 603, and the optical receivers 650 are placed on the dielectric non-conductive substrate.

Each driver of the driver array 602 receives at its inputs (not shown in Fig. 6) an electric signal from, for instance, a motherboard of a computer (not shown in Fig. 6), converts the received electrical signal into a single ended electrical signal and outputs this via output terminals 610 and 611 to inputs of a laser diode of the array of laser diodes 603. The output terminal 611 of a driver of the driver array 602 is connected via a ground line 613 to an input of a respective laser diode of the array of laser diodes 603. The output terminal 610 of a driver of the driver array 602 is connected via a signal line 612 to another input of the respective laser diode. Each laser diode of the array of laser diodes 603 converts the single ended electrical signal received at its inputs to an optical signal, and outputs this to an optical fibre.

As each opening 615 provided in the ground plane 601 of the transceiver 600 has a resonance frequency that is sufficiently higher than 3 times of the fundamental frequency corresponding to the 25 Gbps data communication, none of the openings 615 exhibits a resonance effect at 38 GHz, and in consequence, do not attract current from the Driver-VCSEL channels of the transceiver 600. Therefore, crosstalk in the PIN-TIA channels of the optical receiver 615 is reduced to a tolerable value.

Referring now to Fig. 7, a fourth advantageous embodiment of the present invention is shown. Fig. 7 shows a transceiver 700 differing from the transceiver 600 in that it includes the optical receiver according to the second embodiment instead of the optical receiver according to the first embodiment. The optical receiver of the second embodiment is encircled by the dotted line 751. As the optical receiver of the second embodiment reduces crosstalk in the PIN-TIA channels more efficiently than the optical receiver of the first embodiment, the transceiver 700 reduces crosstalk from the Driver-VCSEL channels into the PIN-TIA channels more efficiently than the transceiver 600.

In the transceivers 600 and 700, the fundamental frequency of the single ended electrical signals output by the drivers of the array of drivers 602, which corresponds to the fundamental frequency of the signal to be transmitted, is identical to the fundamental frequency of the optical signals received at the photodiodes of the optical receiver. In the case of a 25 Gbps data communication, the fundamental frequency of the signals to be transmitted/received is 12.5 GHz. However, the present invention is not limited to 12.5 GHz, but is also applicable to other fundamental frequencies of the signals to be transmitted/received. In this case, however, the dimensions of the openings 415, 515 and 525 have to be changed accordingly.

Also, a transceiver according to the present invention is not limited to the case where the fundamental frequency of the signals to be transmitted is identical to the fundamental frequency of the signals to be received. On the contrary, it is conceivable that the fundamental frequency of the signals to be transmitted is different from the fundamental frequency of the signals to be received.

Fig. 8 shows a layout/design 800 of a mask for an optical receiver according to the second embodiment, cf. Fig. 5. Reference numeral 814 denotes a PIN diode corresponding to the photodiode 514 in Fig. 5. Reference numerals 816 and 817 denote the cathode and the anode of the PIN diode 814. Reference numeral 818 denotes the inputs of the TIA connected with the PIN diode 812. The TIAs and the connection lines with the PIN diodes are not shown in Fig. 8. Reference numeral 815 denotes a first opening corresponding to the first opening 515 in Fig. 5. Reference numeral 825 denotes a second opening corresponding to the second opening 525 in Fig. 5. The horizontal and oblique-regions in Fig. 8 represent ground planes corresponding to the ground plane 501 in Fig. 5.

Fig. 10 shows the principle s-parameter coupling coefficient corresponding to the single end type crosstalk from the driver outputs of the driver array 702 to the input of the TIA that is closest to the driver array 702. This is obtained by simulation for the transceiver 700 having all Driver-VCSEL channels activated. The principle s-parameter coupling coefficient 901 does not show a broad resonance at 37.5 GHz. On the contrary, its level at about 37.5 GHz is reduced by 15 dB as compared to Fig. 2. Hence, crosstalk in the TIA input closest to the driver array 102 is significantly reduced. This becomes also evident

from Fig. 10, which shows the EYE diagram corresponding to 25 Gbps, for the PIN-TIA channel closest to the driver array 702. The crosstalk in the PIN-TIA channel closest to the driver array 702 generates less than 2 ps or 0.05 UI Jitter in the EYE diagram for 25 Gbps, assuming a bit error rate (BER) of  $10^{-12}$ . The outline 1001 corresponds to a bit error rate of  $10^{-12}$ . The EYE diagram in Fig. 10 has been obtained by simulation under similar conditions as the EYE diagram in Fig. 2, i.e. the transceiver 100 has all four aggressor channels activated and the ratio between driver output and TIA input current is equal to 100, which corresponds to about -8 dBm optical receiver sensitivity.

Although the optical receivers shown in Figs. 4 and 5 have four PIN-TIA channels, the present invention is not limited to optical receivers with four PIN-TIA channels, but is also applicable to optical receivers having an arbitrary number of PIN-TIA channels.

Although the transceivers shown in Figs. 6 and 7 have four Driver-VCSEL channels and four PIN-TIA channels, the present invention is not limited to transceivers with four Driver-VCSEL channels and four PIN-TIA channels, but is also applicable to transceivers having an arbitrary number of Driver-VCSEL channels and an arbitrary number of PIN-TIA channels.

Although the openings provided in the ground planes of the optical receivers according to the first and second embodiments have a rectangular shape, the present invention is not limited to openings having a rectangular shape, but is also applicable to openings having a circular shape, an oval shape, a rhombic shape, or any other shape. It is merely important that the resonance frequency of the openings is sufficiently higher than three times the fundamental frequency of the signal that induces crosstalk in the PIN-TIA channel.

**Reference Numerals**

| <b>Reference Numeral</b> | <b>Description</b>                                                                 |
|--------------------------|------------------------------------------------------------------------------------|
| 100, 600, 700            | Transceiver                                                                        |
| 101, 401, 501, 601       | Ground plane                                                                       |
| 102, 602, 702            | Driver Array                                                                       |
| 103, 603                 | Array of laser diodes (VCSELs)                                                     |
| 104, 404, 504, 604       | Array of photodiodes (PINs)                                                        |
| 105, 405, 605            | Array of amplifiers (TIAs)                                                         |
| 110, 610                 | Driver output (signal)                                                             |
| 111, 611                 | Driver output (ground)                                                             |
| 112, 612                 | Single ended signal line                                                           |
| 113, 613                 | Ground line                                                                        |
| 114, 414, 514, 614       | Photodiode (PIN)                                                                   |
| 115, 415, 515, 615       | Opening/First opening in ground plane                                              |
| 116, 416                 | Cathode of photodiode (PIN)                                                        |
| 117, 417                 | Anode of photodiode (PIN)                                                          |
| 118, 418                 | Single ended signal line                                                           |
| 119, 419                 | Ground line                                                                        |
| 201, 901                 | S-parameter coupling coefficient                                                   |
| 202                      | Resonance peak at 38 GHz                                                           |
| 301, 1001                | Outline corresponding to BER = $10^{-12}$                                          |
| 400, 500, 650            | Optical receiver                                                                   |
| 525                      | Second opening in ground plane                                                     |
| 530                      | Strip line delimiting the first opening and the second opening in the ground plane |
| 651, 751                 | Doted lines delimiting the optical receiver                                        |
| 814                      | Input of photodiode (PIN)                                                          |
| 815                      | First Opening in ground plane                                                      |
| 816                      | Cathode of photodiode (PIN)                                                        |
| 817                      | Anode of photodiode (PIN)                                                          |
| 825                      | Second opening in ground plane                                                     |
| 880                      | Amplifier (TIA) inputs                                                             |

**CLAIMS**

1. An optical receiver for receiving at least one optical signal, comprising:
  - a dielectric non-conductive substrate,
  - 5 a ground plane placed on the dielectric non-conductive substrate,
  - at least one photodiode placed on the dielectric non-conductive substrate, wherein the at least one photodiode is adapted to receive the at least one optical signal, to convert the received optical signal in an electrical signal, and to output the electrical signal,
  - 10 at least one amplifier adapted to receive at an input thereof the electrical signal output by the at least one photodiode, and
  - at least one first opening provided in the ground plane,
  - wherein the at least one first opening surrounds the at least one photodiode, and
  - 15 the at least one first opening has a resonance frequency that is sufficiently higher than a predetermined fundamental frequency so as to reduce crosstalk at the input of the amplifier below a predetermined value.
2. The optical receiver according to claim 1, wherein said resonance frequency is sufficiently higher than three times of said predetermined fundamental frequency.
- 20 3. The optical receiver according to claim 2, wherein said resonance frequency is 50 GHz or more.
4. The optical receiver according to any of claims 1 to 3, wherein the predetermined fundamental frequency corresponds to the fundamental frequency of the at least one optical signal.

5. The optical receiver according to any of claims 1 to 4, wherein the electrical signal received at the input of the at least one amplifier is single ended.

6. The optical receiver according to any of claims 1 to 5, further comprising at least one second opening provided in the ground plane, wherein the at least one second opening  
5 does not surround a photodiode and is placed next to the at least one first opening.

7. The optical receiver according to claim 1 or 2, wherein the optical receiver is adapted to receive a plurality of optical signals of the same fundamental frequency, the optical receiver comprises:

10 a plurality of photodiodes placed on the dielectric non-conductive substrate, wherein each photodiode of the plurality of photodiodes is adapted to receive an optical signal of the plurality of optical signals, to convert the received optical signal in a respective electrical signal, and to output the respective electrical signal,

15 a plurality of amplifiers, wherein each amplifier of the plurality of amplifiers is adapted to receive at an input thereof an electrical signal output by a respective photodiode of the plurality of photodiodes,

a plurality of first openings provided in the ground plane,

wherein each opening of the plurality of first openings surrounds at least one photodiode of the plurality of photodiodes, and

20 each opening of the plurality of first openings has a resonance frequency that is sufficiently higher than three times of the predetermined fundamental frequency so as to reduce crosstalk at the input of each amplifier of the plurality of amplifiers below a predetermined value.

8. The optical receiver according to claim 7, wherein the predetermined fundamental frequency corresponds to the fundamental frequency of the plurality of optical signals.

25 9. The optical receiver according to claim 7 or 8, wherein the plurality of optical signals includes four optical signals, the plurality of diodes includes four diodes, the

plurality of amplifiers includes four amplifiers, the plurality of first openings includes four first openings, and the predetermined fundamental frequency is 12.5 GHz.

10. The optical receiver according to claim 9, wherein each opening of the four first openings has a substantially rectangular shape and dimensions of approximately 0.3 mm times 0.25 mm.

11. The optical receiver according to any of claims 7 to 10, wherein the plurality of photodiodes and/or the plurality of amplifiers is linearly arranged in an array.

12. The optical receiver according to any of claims 7 to 11, further comprising a plurality of second openings provided in the ground plane, wherein each opening of the plurality of second openings does not surround a photodiode and is placed next to an opening of the plurality of first openings.

13. The optical receiver according to any of claims 1 to 12, wherein the optical receiver is adapted to receive data at a predetermined bit rate, and the predetermined fundamental frequency corresponds to the predetermined bit rate.

14. A transceiver comprises:

an optical receiver according to any of claims 1 to 6,

at least one laser diode,

at least one driver adapted to output a single ended electric signal to an input of the at least one laser diode,

wherein the fundamental frequency of the single ended electric signal output by the at least one driver corresponds to the predetermined fundamental frequency,

the at least one laser diode is adapted to output an optical signal in accordance with the single ended electric signal received at its input, and

the optical receiver, the at least one driver and the at least one laser diode are provided on the dielectric non-conductive substrate and surrounded by the ground plane.

15. A transceiver comprises:

5 an optical receiver according to any of claims 7 to 12,

a plurality of laser diodes,

a plurality of drivers, each driver of the plurality of drivers is adapted to output a single ended electrical signal to an input of a laser diode of the plurality of laser diodes,

10 wherein the fundamental frequency of the single ended electric signals output by the drivers of the plurality of drivers corresponds to the predetermined fundamental frequency,

each laser diode of the plurality of laser diodes is adapted to output an optical signal in accordance with the single ended electrical signal received at its input, and  
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the optical receiver, the plurality of drivers and the plurality of laser diodes are provided on the dielectric non-conductive substrate and surrounded by the ground plane.